

### Remarks

Claims 1-13 & 21-23 are at issue. Claims 14-20 have been cancelled as non-elected claims. Claim 21 stands rejected under 35 USC 102(b) as being anticipated by Lueng et al (US 5,563,762). Claims 1-5 stand rejected under 35 USC 103 (a) as being unpatentable over McMillan et al (US 6404003) in view of Uemote et al (US 2001/0019874). Claims 1, 2, 4 & 5 stand rejected under 35 USC 103(a) as being unpatentable over Lueng et al (5,563,762) in view of Duncombe et al (US 2003/0085447). Claim 6 stands rejected under 35 USC 103 (a) as being unpatentable over Lueng et al (5,563,762) in view of Duncombe et al (US 2003/0085447) and further in view of Matsunaga (JP-55166947). Claims 7, 9-11, 22 stand rejected under 35 USC 103(a) as being unpatentable over Lueng et al (5,563,762) in view of Uemoto et al (US 2001/0019874). Claim 23 stands rejected under 35 USC 103(a) as being unpatentable over Lueng et al (5,563,762) in view of Duncombe et al (US 2003/0085447). Claim 12 & 13 stand rejected under 35 USC 103(a) as being unpatentable over Lueng et al (5,563,762) in view of Uemotot etl al (US 2001/0019874) and further in view of Hashemi (US 5,049,979).

Claim 6 was rejected under 35 USC 112 first paragraph. The applicants respectfully disagree with the Examiner. The process of reflowing solder to form bumps for a surface mounted integrated circuit is well known to those skilled in the art. Page 7, lines 23-26 and page 8, lines 24 & 25 of the specification discuss how the present decoupling capacitor may be reflowed to form a bump on an IC.

Claim 1 requires that the nickel electrode be electrically connected to the aluminum lead of the IC. Aluminum will become very soft above 450 degrees centigrade and if heated above this temperature may result in discontinuities. (See specification Page 6, lines 8-10) McMillan et al state in the abstract that they anneal the capacitor at a temperature above 600 degrees centigrade. Clearly they are not electrically coupled to aluminum. Uemoto also requires heating the dielectric to a temperature of 650 degees centigrade. So Uemoto is inapplicable to the present invention.

The Examiner also points to Leung. But Leung does not disclose the use of BCTZ as the dielectric. Claim 1 is allowable.

Claim 7 requires that the nickel electrode be electrically connected to the aluminum lead of the IC. Aluminum will become very soft above 450 degrees centigrade and if heated above this temperature may result in discontinuities. (See specification Page 6, lines 8-10) McMillan et al state in the abstract that they anneal the capacitor at a temperature above 600 degrees centigrade. Clearly they are not electrically coupled to aluminum. Uemoto also requires heating the dielectric to a temperature of 650 degrees centigrade. So Uemoto is inapplicable to the present invention.

The Examiner also points to Leung. But Leung does not disclose the use of BCTZ as the dielectric. Claim 7 is allowable.

Claim 21 requires that the nickel electrode be electrically connected to the aluminum lead of the IC. Aluminum will become very soft above 450 degrees centigrade and if heated above this temperature may result in discontinuities. (See specification Page 6, lines 8-10) McMillan et al state in the abstract that they anneal the capacitor at a temperature above 600 degrees centigrade. Clearly they are not electrically coupled to aluminum. Uemoto also requires heating the dielectric to a temperature of 650 degrees centigrade. So Uemoto is inapplicable to the present invention.

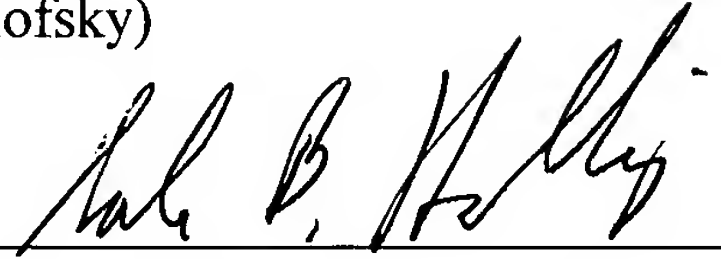
The Examiner also points to Leung. But Leung does not disclose the use of BCTZ as the dielectric. Claim 21 is allowable.

All the other claims are allowable as being dependent upon an allowable base claim.

Prompt reconsideration and allowance are respectfully requested.

Respectfully submitted,

(Philofsky)

By 

Attorney for the Applicant

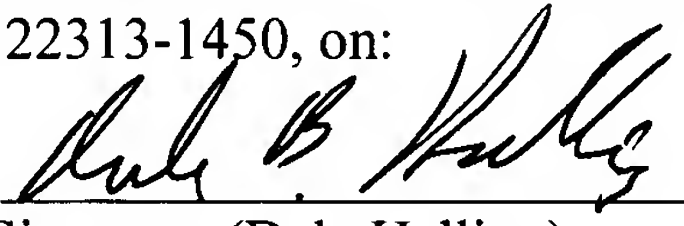
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